Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1.   (Currently Amended) A method of manufacturing an electronic device, the method comprising:

forming an external terminal on an interconnect pattern formed on a substrate;

subsequently mounting a chip component on the substrate face up, the chip component having an electrode on a first surface of the chip component opposite to a second surface facing the substrate;

forming an insulating section adjacent to the chip component; and

forming <u>by inkjet</u> an interconnect on the insulating section from the electrode to the interconnect pattern for electrically connecting the electrode and the interconnect pattern at a temperature lower than a melting point of the external terminal.

2.   (Original) The method of manufacturing an electronic device as defined by claim 1,

wherein the interconnect is formed of a dispersant including electrically conductive particles.

3.   (Previously Presented) The method of manufacturing an electronic device as defined by claim 2,

wherein the step of forming the interconnect includes ejecting a dispersant including the electrically conductive particles over the insulating section and the interconnect pattern.

4.   (Previously Presented) The method of manufacturing an electronic device as defined by claim1, wherein the insulating section is formed of a resin.

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5.   (Previously Presented) The method of manufacturing an electronic device as defined by claim 1,

wherein the insulating section is formed to have an inclined surface descending in an outward direction from the chip component.

6.   (Original) The method of manufacturing an electronic device as defined by claim 4,

wherein the insulating section is formed to have an inclined surface descending in an outward direction from the chip component.

7.   (Original) The method of manufacturing an electronic device as defined by claim 1,

wherein the chip component is a semiconductor element.

8-11. (Canceled)